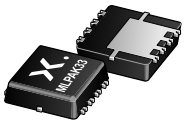

# BUK9Q7R0-40H

## Logic level N-Channel MOSFET in MLPAK33-WF (SOT8002-3D)

**7 May 2025** **Product data sheet**

## 1. General description

Logic level N-Channel MOSFET in a small MLPAK33-WF (SOT8002-3D) package using Trench 9 technology. This product has been designed and qualified to meet AEC-Q101 requirements delivering high performance and reliability.

## 2. Features and benefits

- Trench 9 technology
- Small footprint (3 x 3 mm) for compact design
- Qualified to AEC-Q101 at 175 °C
- Side-wettable flanks for robust solder joints and automated optical inspection

## 3. Applications

- Motor drive
- Battery protection
- DC-DC conversion

## 4. Quick reference data

**Table 1. Quick reference data**

| Symbol | Parameter | Conditions | | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|---|
| $V_{DS}$ | drain-source voltage | 25 °C ≤ $T_j$ ≤ 175 °C | | - | - | 40 | V |
| $I_D$ | drain current | $V_{GS}$ = 5 V; $T_{mb}$ = 25 °C; Fig. 2 | | - | - | 62 | A |
| $P_{tot}$ | total power dissipation | $T_{mb}$ = 25 °C; Fig. 1 | | - | - | 53 | W |
| **Static characteristics** | | | | | | | |
| $R_{DSon}$ | drain-source on-state resistance | $V_{GS}$ = 10 V; $I_D$ = 20 A; $T_j$ = 25 °C; Fig. 11 | | 4 | 5.8 | 7 | mΩ |
| **Dynamic characteristics** | | | | | | | |
| $Q_{GD}$ | gate-drain charge | $I_D$ = 15 A; $V_{DS}$ = 20 V; $V_{GS}$ = 4.5 V; $T_j$ = 25 °C; Fig. 13; Fig. 14 | | - | 2.4 | 4.9 | nC |

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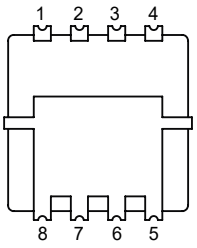
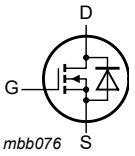
# 5. Pinning information

**Table 2. Pinning information**

| Pin | Symbol | Description | Simplified outline | Graphic symbol |
|---|---|---|---|---|
| 1 | S | source |  MLPAK33 (SOT8002-3) |  |
| 2 | S | source | | |
| 3 | S | source | | |
| 4 | G | gate | | |
| mb | D | Mounting base; connected to drain | | |

# 6. Ordering information

**Table 3. Ordering information**

| Type number | Package | | |
|---|---|---|---|
| | Name | Description | Version |
| BUK9Q7R0-40H | MLPAK33 | plastic thermal enhanced surface mounted package with side-wettable flanks (SWF); mini leads; 8 terminals;pitch 0.65 mm; 3.3 x 3.3 x 0.8 mm body | SOT8002-3 |

# 7. Marking

**Table 4. Marking codes**

| Type number | Marking code |
|---|---|
| BUK9Q7R0-40H | 6AU |

# 8. Limiting values

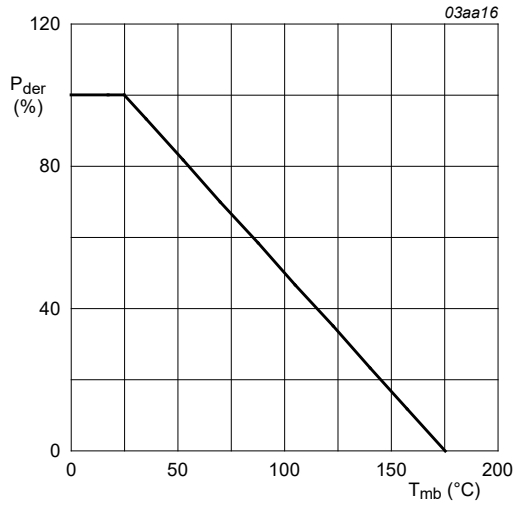
**Table 5. Limiting values**

*In accordance with the Absolute Maximum Rating System (IEC 60134).Tj = 25 °C unless otherwise stated.*

| Symbol | Parameter | Conditions | | Min | Max | Unit |
|---|---|---|---|---|---|---|
| $V_{DS}$ | drain-source voltage | 25 °C ≤ $T_j$ ≤ 175 °C | | - | 40 | V |
| $V_{GS}$ | gate-source voltage | | | -20 | 20 | V |
| $P_{tot}$ | total power dissipation | $T_{mb}$ = 25 °C; Fig. 1 | | - | 53 | W |
| $I_D$ | drain current | $V_{GS}$ = 5 V; $T_{mb}$ = 25 °C; Fig. 2 | | - | 62 | A |
| | | $V_{GS}$ = 5 V; $T_{mb}$ = 100 °C; Fig. 2 | | - | 44 | A |
| $I_{DM}$ | peak drain current | pulsed; $t_p$ ≤ 10 µs; $T_{mb}$ = 25 °C; Fig. 3 | | - | 250 | A |
| $T_{stg}$ | storage temperature | | | -55 | 175 | °C |
| $T_j$ | junction temperature | | | -55 | 175 | °C |
| **Source-drain diode** | | | | | | |
| $I_S$ | source current | $T_{mb}$ = 25 °C | | - | 44 | A |
| $I_{SM}$ | peak source current | pulsed; $t_p$ ≤ 10 µs; $T_{mb}$ = 25 °C | | - | 250 | A |

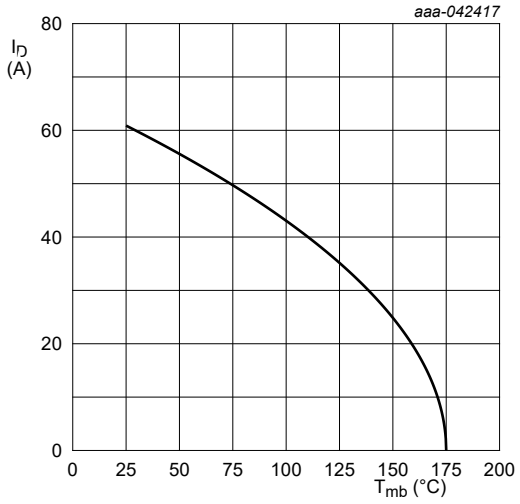
| Symbol | Parameter | Conditions | | Min | Max | Unit |
|---|---|---|---|---|---|---|
| **Avalanche ruggedness** | | | | | | |
| $E_{DS(AL)S}$ | non-repetitive drain-source avalanche energy | $I_D$ = 26.8 A; $V_{sup}$ ≤ 40 V; $R_{GS}$ = 50 Ω; $V_{GS}$ = 5 V; $T_{j(init)}$ = 25 °C; unclamped; $t_p$ = 96 µs; Fig. 4 | [1] [2] | - | 67 | mJ |
| $I_{AS}$ | non-repetitive avalanche current | $V_{sup}$ = 40 V; $V_{GS}$ = 5 V; $T_{j(init)}$ = 25 °C; $R_{GS}$ = 50 Ω; Fig. 4 | [3] | - | 50 | A |

[1] Single-pulse avalanche rating limited by maximum junction temperature of 175 °C.
[2] Refer to application note AN10273 for further information.
[3] Protected by 100% test



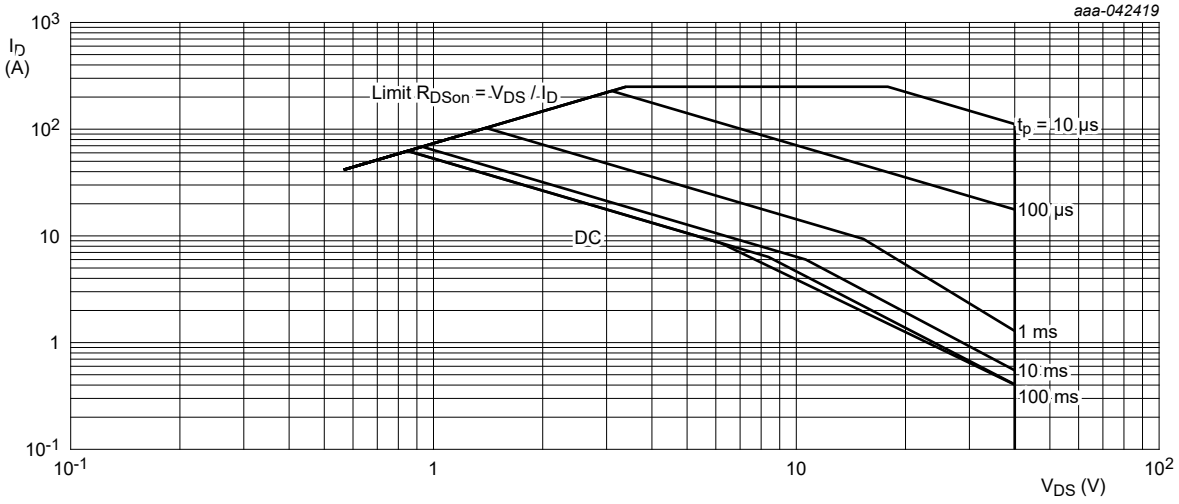

$$P_{der} = \frac{P_{tot}}{P_{tot(25°C)}} \times 100\ \%$$

**Fig. 1. Normalized total power dissipation as a function of mounting base temperature**



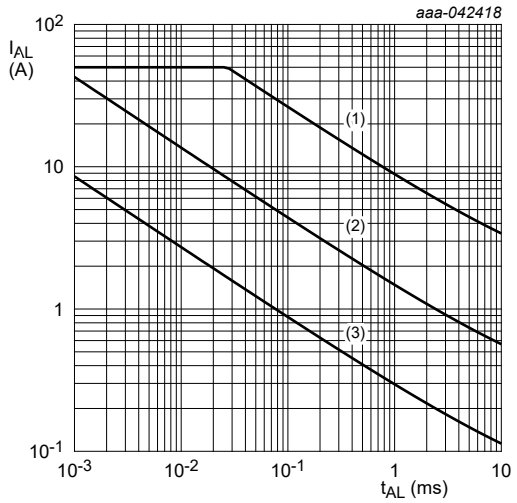

$V_{GS}$ ≥ 5 V

**Fig. 2. Continuous drain current as a function of mounting base temperature**




$T_{mb}$ = 25 °C; $I_{DM}$ is a single pulse

**Fig. 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage**




(1) $T_{j\ (init)}$ = 25 °C; (2) $T_{j\ (init)}$ = 150 °C; (3) Repetitive Avalanche

**Fig. 4. Avalanche rating; avalanche current as a function of avalanche time**

# 9. Thermal characteristics

**Table 6. Thermal characteristics**

| Symbol | Parameter | Conditions | | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|---|
| $R_{th(j\text{-}mb)}$ | thermal resistance from junction to mounting base | Fig. 5 | | - | 2.35 | 2.83 | K/W |
| $R_{th(j\text{-}a)}$ | thermal resistance from junction to ambient | | [1] | - | - | 40 | K/W |

[1] Device on 4 layer PCB. Refer to TN00008 for further information.

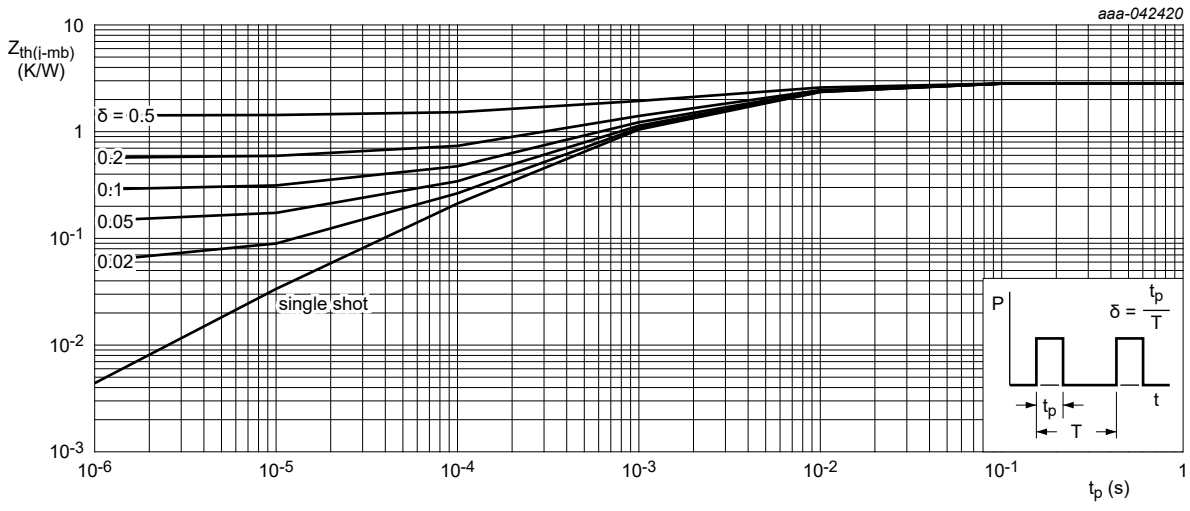



**Fig. 5. Transient thermal impedance from junction to mounting base as a function of pulse duration**

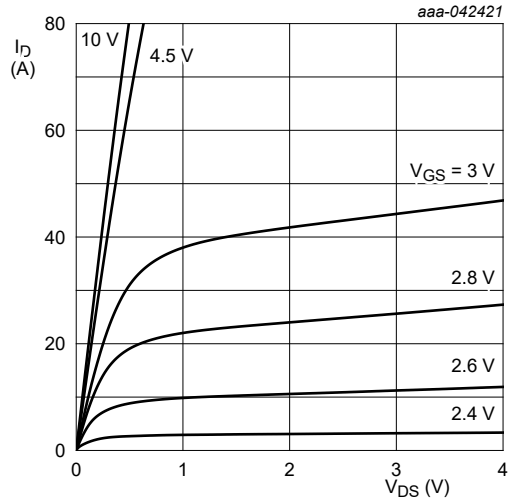
# 10. Characteristics

**Table 7. Characteristics**

| Symbol | Parameter | Conditions | | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|---|
| **Static characteristics** | | | | | | | |
| $V_{(BR)DSS}$ | drain-source breakdown voltage | $I_D$ = 250 µA; $V_{GS}$ = 0 V; $T_j$ = 25 °C | | 40 | 44 | - | V |
| | | $I_D$ = 250 µA; $V_{GS}$ = 0 V; $T_j$ = -40 °C | | - | 40.5 | - | V |
| | | $I_D$ = 250 µA; $V_{GS}$ = 0 V; $T_j$ = -55 °C | | 36 | 40 | - | V |
| $V_{GS(th)}$ | gate-source threshold voltage | $I_D$ = 1 mA; $V_{DS}$=$V_{GS}$; $T_j$ = 25 °C; Fig. 9; Fig. 10 | | 1.35 | 1.7 | 2.05 | V |
| | | $I_D$ = 1 mA; $V_{DS}$=$V_{GS}$; $T_j$ = 175 °C; Fig. 10 | | 0.7 | - | - | V |
| | | $I_D$ = 1 mA; $V_{DS}$=$V_{GS}$; $T_j$ = -55 °C; Fig. 10 | | - | - | 2.6 | V |
| $I_{DSS}$ | drain leakage current | $V_{DS}$ = 40 V; $V_{GS}$ = 0 V; $T_j$ = 25 °C | | - | 0.002 | 1 | µA |
| | | $V_{DS}$ = 40 V; $V_{GS}$ = 0 V; $T_j$ = 175 °C | | - | - | 500 | µA |
| $I_{GSS}$ | gate leakage current | $V_{GS}$ = 20 V; $V_{DS}$ = 0 V; $T_j$ = 25 °C | | - | 2 | 100 | nA |
| | | $V_{GS}$ = -20 V; $V_{DS}$ = 0 V; $T_j$ = 25 °C | | - | 2 | 100 | nA |
| $R_{DSon}$ | drain-source on-state resistance | $V_{GS}$ = 10 V; $I_D$ = 20 A; $T_j$ = 25 °C; Fig. 11 | | 4 | 5.8 | 7 | mΩ |
| | | $V_{GS}$ = 10 V; $I_D$ = 20 A; $T_j$ = 105 °C; Fig. 12 | | 5.7 | 8.2 | 10.4 | mΩ |
| | | $V_{GS}$ = 10 V; $I_D$ = 20 A; $T_j$ = 125 °C; Fig. 12 | | 6.2 | 8.9 | 11.3 | mΩ |
| | | $V_{GS}$ = 10 V; $I_D$ = 20 A; $T_j$ = 175 °C; Fig. 12 | | 7.5 | 10.7 | 13.4 | mΩ |
| | | $V_{GS}$ = 4.5 V; $I_D$ = 20 A; $T_j$ = 25 °C; Fig. 11 | | 5 | 7.1 | 9.1 | mΩ |
| | | $V_{GS}$ = 4.5 V; $I_D$ = 20 A; $T_j$ = 105 °C; Fig. 12 | | 7 | 10 | 13.5 | mΩ |
| | | $V_{GS}$ = 4.5 V; $I_D$ = 20 A; $T_j$ = 125 °C; Fig. 12 | | 7.5 | 10.7 | 14.7 | mΩ |
| | | $V_{GS}$ = 4.5 V; $I_D$ = 20 A; $T_j$ = 175 °C; Fig. 12 | | 9 | 13 | 17.4 | mΩ |
| $R_G$ | gate resistance | f = 1 MHz; $T_j$ = 25 °C | | 0.9 | 2.2 | 5.5 | Ω |
| **Dynamic characteristics** | | | | | | | |
| $Q_{G(tot)}$ | total gate charge | $I_D$ = 15 A; $V_{DS}$ = 20 V; $V_{GS}$ = 10 V; $T_j$ = 25 °C; Fig. 13; Fig. 14 | | - | 23 | 32 | nC |
| | | $I_D$ = 15 A; $V_{DS}$ = 20 V; $V_{GS}$ = 4.5 V; $T_j$ = 25 °C; Fig. 13; Fig. 14 | | - | 10 | 14.6 | nC |
| $Q_{GS}$ | gate-source charge | | | - | 3.9 | 5.9 | nC |
| $Q_{GD}$ | gate-drain charge | | | - | 2.4 | 4.9 | nC |
| $V_{GS(pl)}$ | gate-source plateau voltage | $I_D$ = 15 A; $V_{DS}$ = 20 V; $T_j$ = 25 °C; Fig. 13; Fig. 14 | | - | 2.7 | - | V |
| $C_{iss}$ | input capacitance | $V_{DS}$ = 25 V; $V_{GS}$ = 0 V; f = 1 MHz; $T_j$ = 25 °C; Fig. 15 | | - | 1520 | 2128 | pF |
| $C_{oss}$ | output capacitance | | | - | 306 | 428 | pF |
| $C_{rss}$ | reverse transfer capacitance | | | - | 65 | 143 | pF |
| $t_{d(on)}$ | turn-on delay time | $V_{DS}$ = 20 V; $R_L$ = 1.333 Ω; $V_{GS}$ = 4.5 V; $R_{G(ext)}$ = 5 Ω; $T_j$ = 25 °C | | - | 11 | - | ns |
| $t_r$ | rise time | | | - | 12 | - | ns |

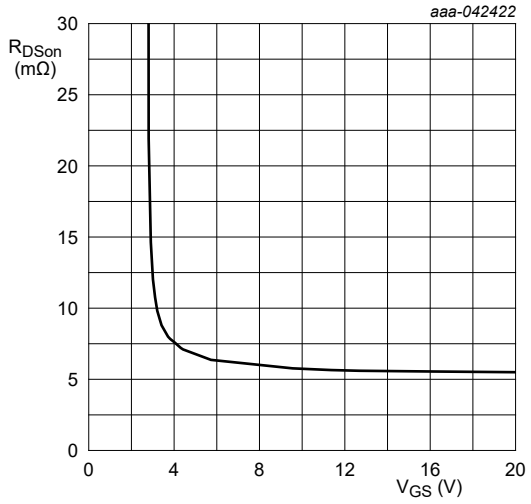
| Symbol | Parameter | Conditions | | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|---|
| $t_{d(off)}$ | turn-off delay time | | | - | 16 | - | ns |
| $t_f$ | fall time | | | - | 8 | - | ns |
| **Source-drain diode** | | | | | | | |
| $V_{SD}$ | source-drain voltage | $I_S$ = 20 A; $V_{GS}$ = 0 V; $T_j$ = 25 °C; Fig. 16 | | - | 0.8 | 1.2 | V |
| $t_{rr}$ | reverse recovery time | $I_S$ = 12 A; $dI_S/dt$ = -100 A/µs; $V_{GS}$ = 0 V; $V_{DS}$ = 20 V; $T_j$ = 25 °C; Fig. 17 | | - | 19 | - | ns |
| $Q_r$ | recovered charge | | [1] | - | 10 | - | nC |

[1] includes capacitive recovery



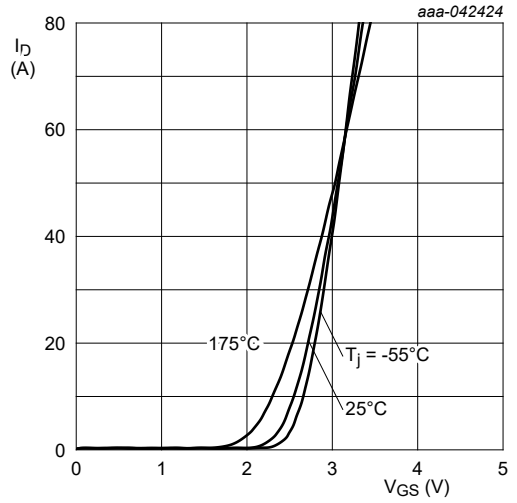

$T_j$ = 25 °C

**Fig. 6. Output characteristics; drain current as a function of drain-source voltage; typical values**



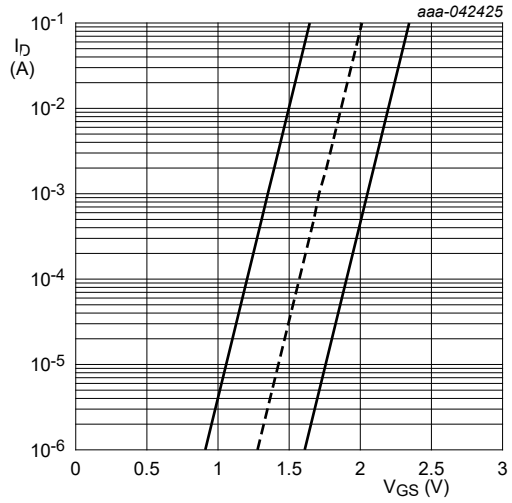

$T_j$ = 25 °C; $I_D$ = 15 A

**Fig. 7. Drain-source on-state resistance as a function of gate-source voltage; typical values**



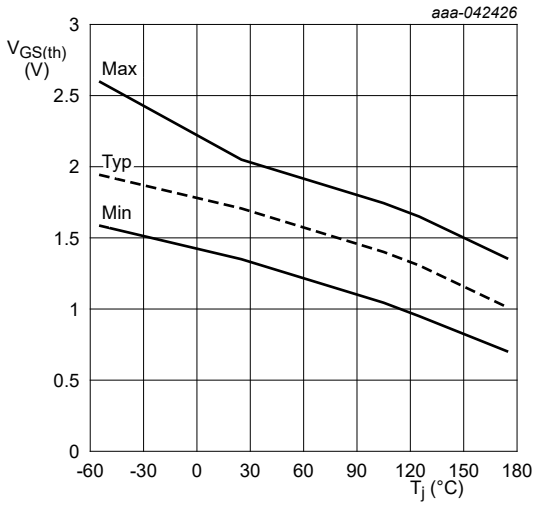

$V_{DS}$ = 8 V

**Fig. 8. Transfer characteristics; drain current as a function of gate-source voltage; typical values**



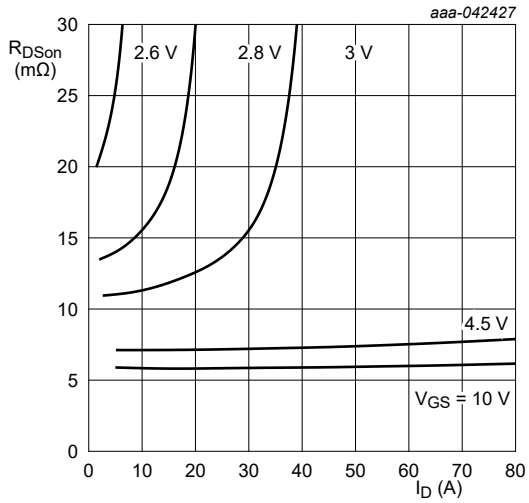

$T_j$ = 25 °C; $V_{DS}$ = 5 V

**Fig. 9. Sub-threshold drain current as a function of gate-source voltage**



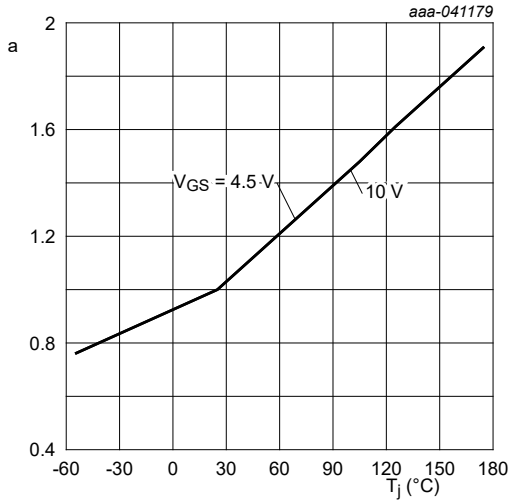

$I_D$ = 1 mA ; $V_{DS}$ = $V_{GS}$

**Fig. 10. Gate-source threshold voltage as a function of junction temperature**



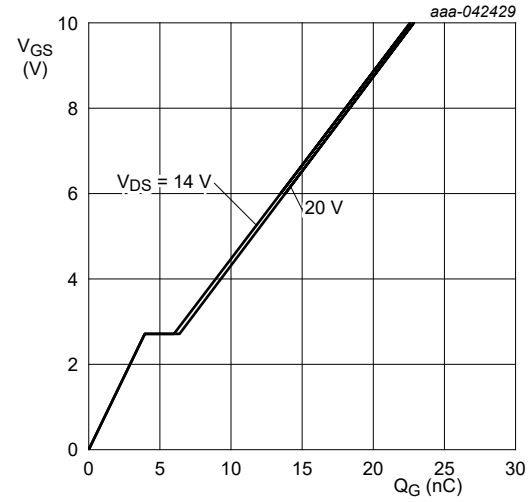

$T_j$ = 25 °C

**Fig. 11. Drain-source on-state resistance as a function of drain current; typical values**




$$a = \frac{R_{DSon}}{R_{DSon\,(25°C)}}$$

**Fig. 12. Normalized drain-source on-state resistance factor as a function of junction temperature**




$T_j$ = 25 °C; $I_D$ = 15 A

**Fig. 13. Gate-source voltage as a function of gate charge; typical values**

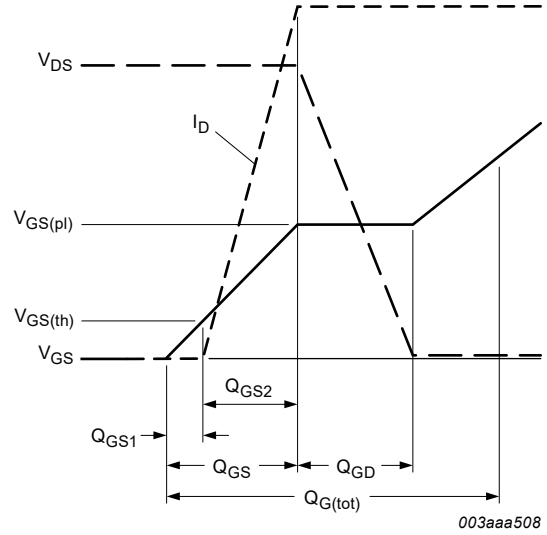
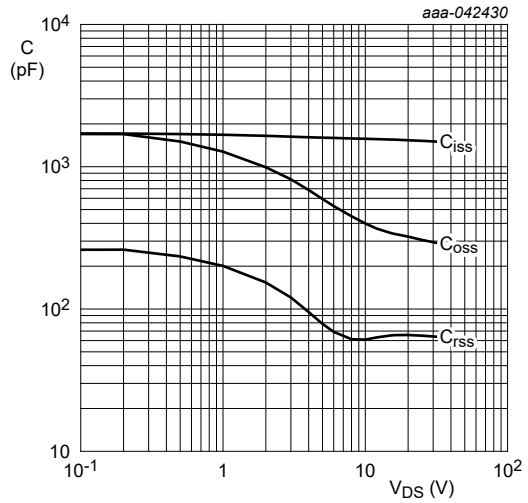
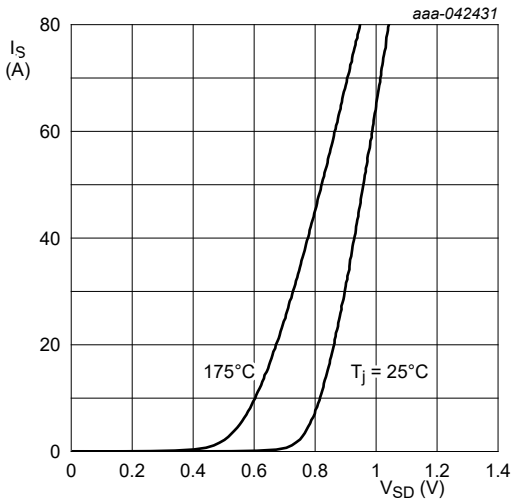



Fig. 14. Gate charge waveform definitions




$V_{GS}$ = 0 V; f = 1 MHz

Fig. 15. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values




$V_{GS}$ = 0 V

Fig. 16. Source-drain (diode forward) current as a function of source-drain (diode forward) voltage; typical values

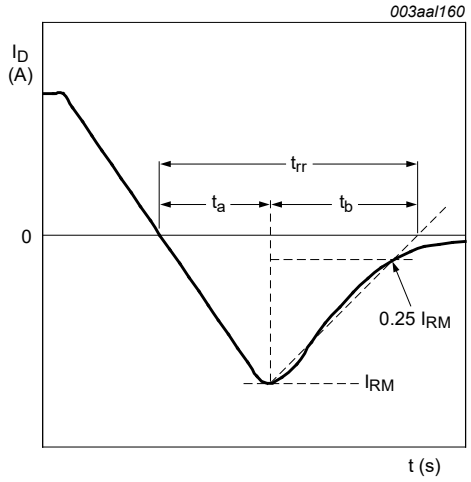
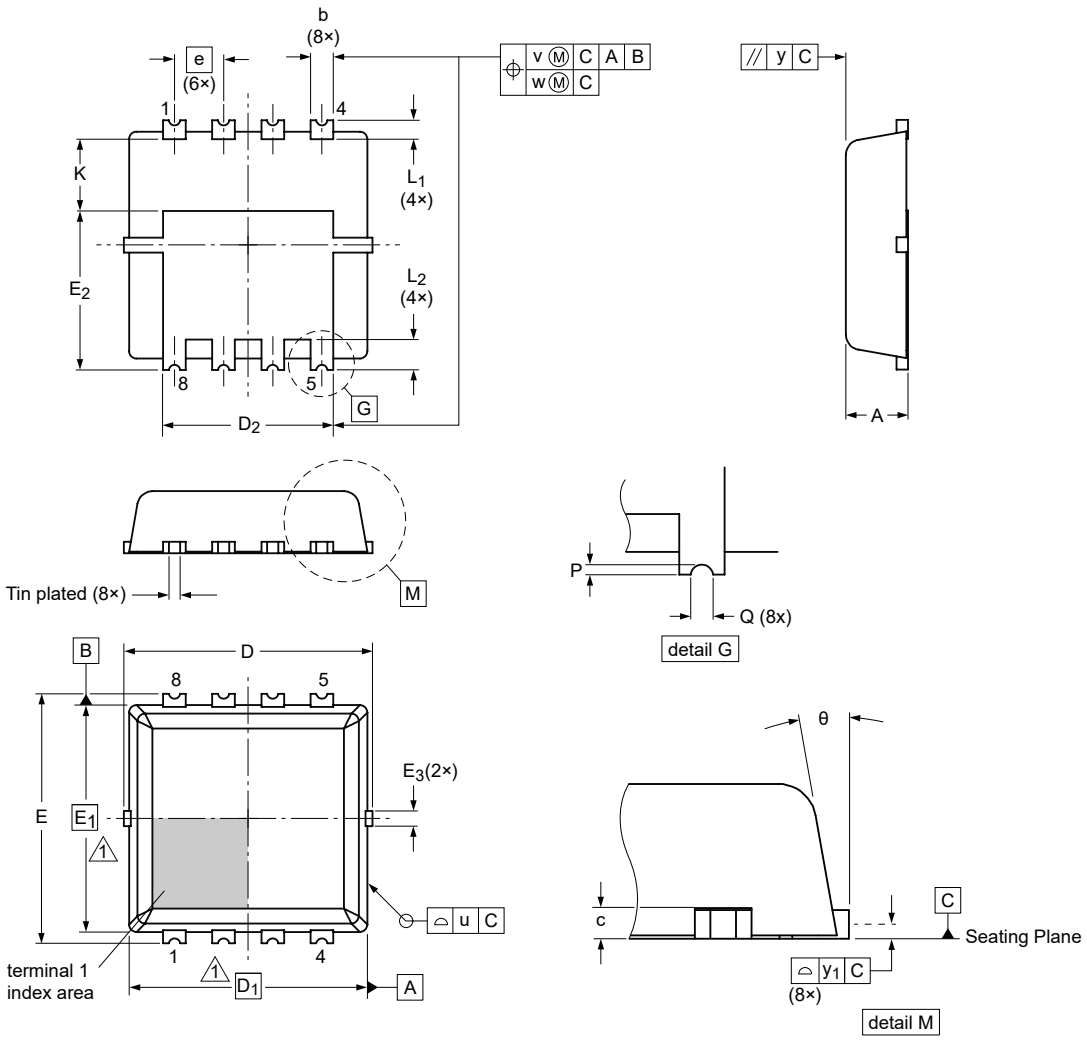



Fig. 17. Reverse recovery timing definition

# 11. Package outline

**MLPAK33: plastic thermal enhanced surface mounted package with side-wettable flanks (SWF); mini leads; 8 terminals;pitch 0.65 mm; 3.3 x 3.3 x 0.8 mm body** **SOT8002-3**




| w |
|---|
| 0.05 |

Dimensions (mm are the original dimensions)

| Unit | | A | b | c | D | $D_1$ | $D_2$ | e | E | $E_1$ | $E_2$ | $E_3$ | K | $L_1$ | $L_2$ | P | Q | θ | y | $y_1$ | u | v |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| mm | max | 0.90 | 0.40 | 0.18 | 3.40 | 3.15 | 2.35 | 0.65 | 3.40 | 3.0 | 2.20 | 0.2 | 0.95 | 0.40 | 0.55 | 0.1 | 0.15 | 12° | 0.05 | 0.05 | 0.1 | 0.1 |
| | nom | 0.80 | 0.32 | 0.15 | 3.30 | BSC | 2.25 | BSC | 3.30 | BSC | 2.10 | REF | REF | 0.25 | 0.40 | REF | REF | 10° | | | | |
| | min | 0.70 | 0.25 | 0.12 | 3.20 | | 2.15 | | 3.20 | | 2.00 | | | 0.10 | 0.25 | | | 8° | | | | |

*sot8002-3_po*

| Outline version | References | | | | European projection | Issue date |
|---|---|---|---|---|---|---|
| | IEC | JEDEC | JEITA | | | |
| SOT8002-3 | | | | | | 23-07-21 |

**Fig. 18. Package outline MLPAK33 (SOT8002-3)**

## 12. Soldering

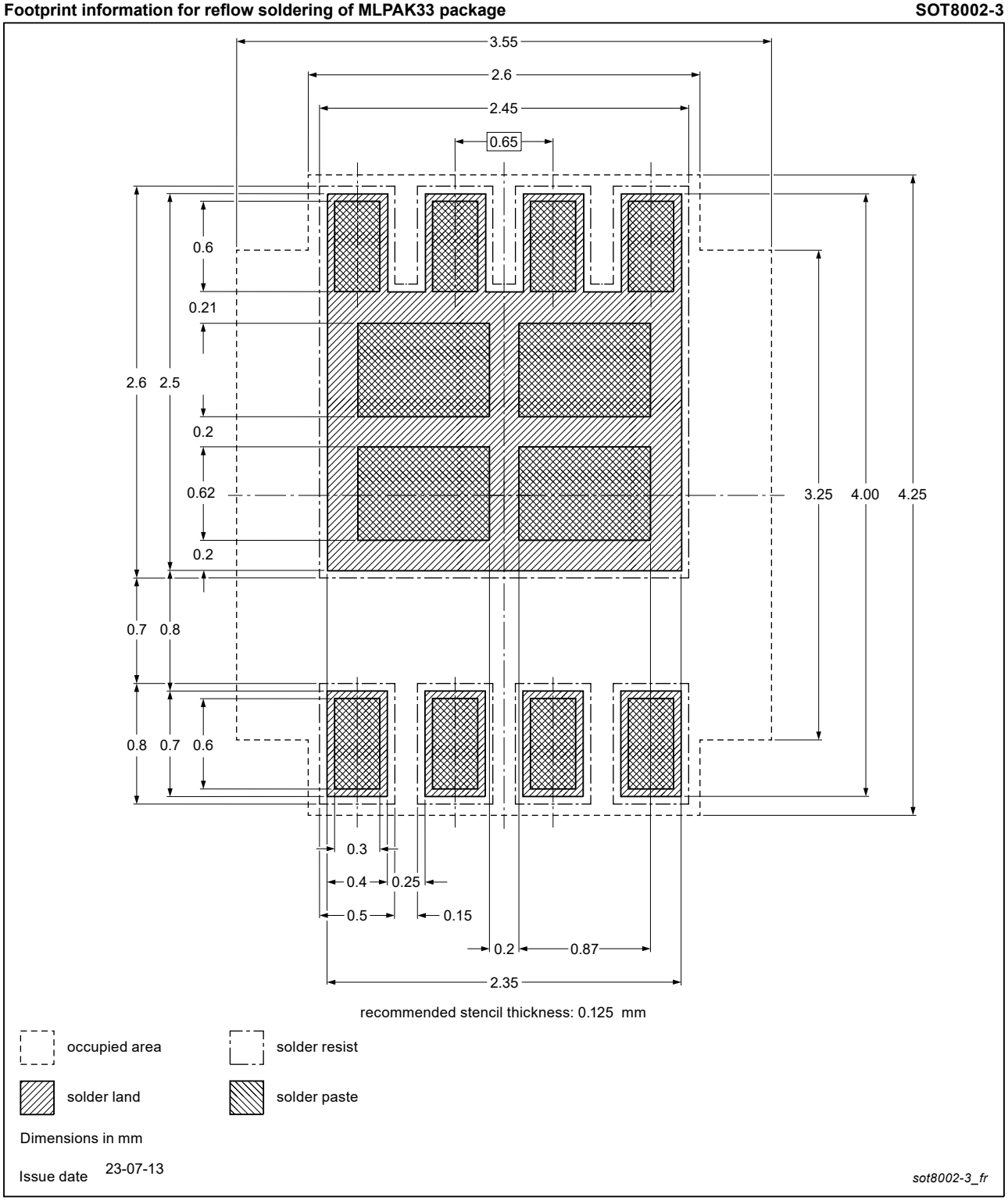



**Fig. 19. Reflow soldering footprint for MLPAK33 (SOT8002-3)**

# 13. Legal information

## Data sheet status

| Document status [1][2] | Product status [3] | Definition |
|---|---|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification | This document contains data from the preliminary specification. |
| Product [short] data sheet | Production | This document contains the product specification. |

[1] Please consult the most recently issued document before initiating or completing a design.
[2] The term 'short data sheet' is explained in section "Definitions".
[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the internet at https://www.nexperia.com.

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